

### DESCRIPTION:

The JOC302XD5 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP5 package with different lead forming options. With the robust coplanar double mold structure, JOC302XD5 series provide the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 120 V<sub>AC</sub> peripherals.

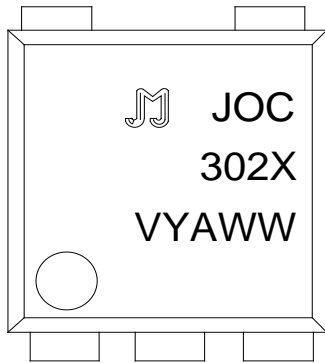
### MAIN FEATURES

High isolation

Junction Temperature	$T_j$	125	
Output Power Dissipation	$P_o$	250	mW
Power Dissipation Derating ( $T_a$ 125 )	$\bullet P_{D/}$	-3.33	mW/

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



## Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

FIG.2: On-state Terminal Current vs. Ambient Temperature  $I_F$ (

FIG.7: Normalized On-state Terminal Voltage vs. Ambient Temperature

FIG.8: On-state Terminal Voltage vs. On-

TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

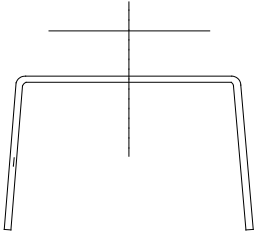
FIG.13: Waveforms of Turn On Time

Fig.14: Test Circuits of  $dV/dt$

Fig.15: Waveforms of  $dV/dt$

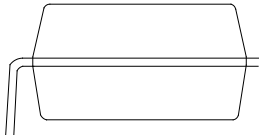
Package Dimension (Unit: mm)

Standard DIP Type:

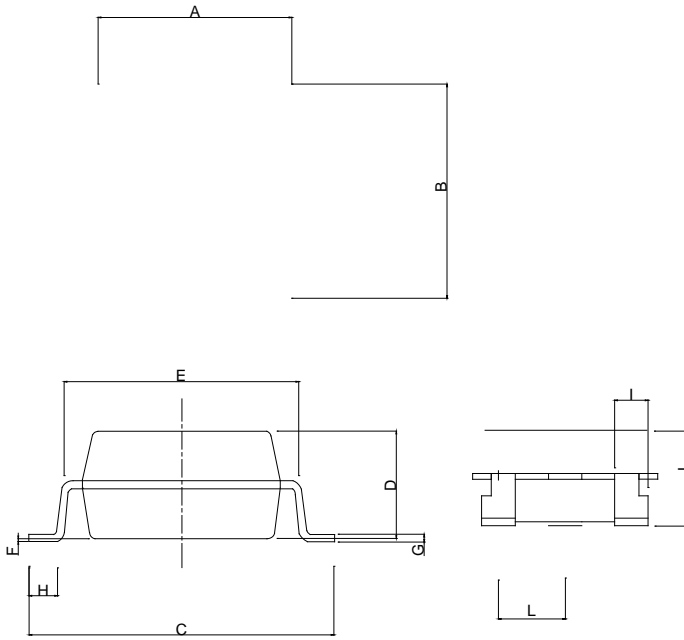


Option S Type:

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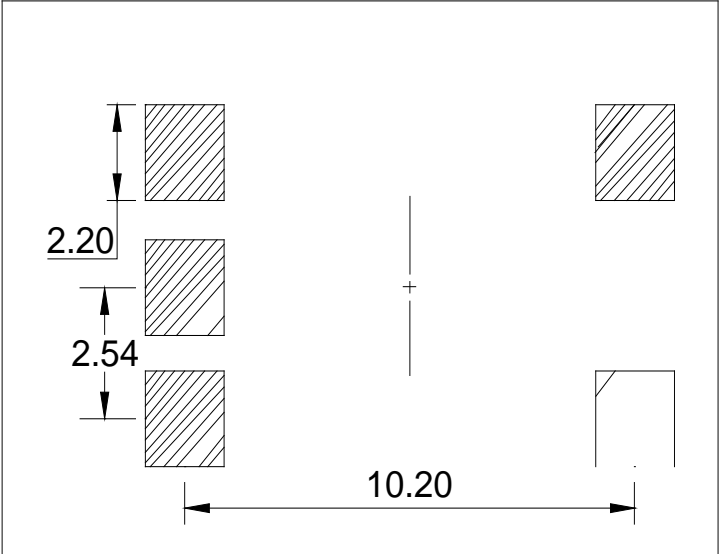


Option SLM Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	6.92		7.32	0.272		0.288
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F			0.30			0.012
G						
H	0.50			0.020		
I	1.10		1.30	0.043		0.051
J	3.45		3.85	0.136		0.152
K						

Option SL



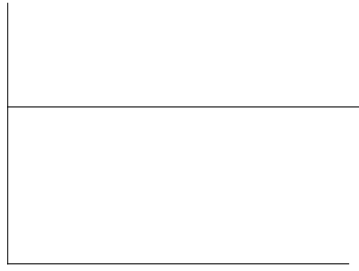
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REFLOW INFORMATION



## WAVE SOLDERING



## HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360± 5
Soldering Time	3s max.

## Document Revision History

Date	Revision	Changes
Apr.2, 2025	A.1.0	Last update
Nov.5, 2025	A.1.1	Add S&SLM package

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